



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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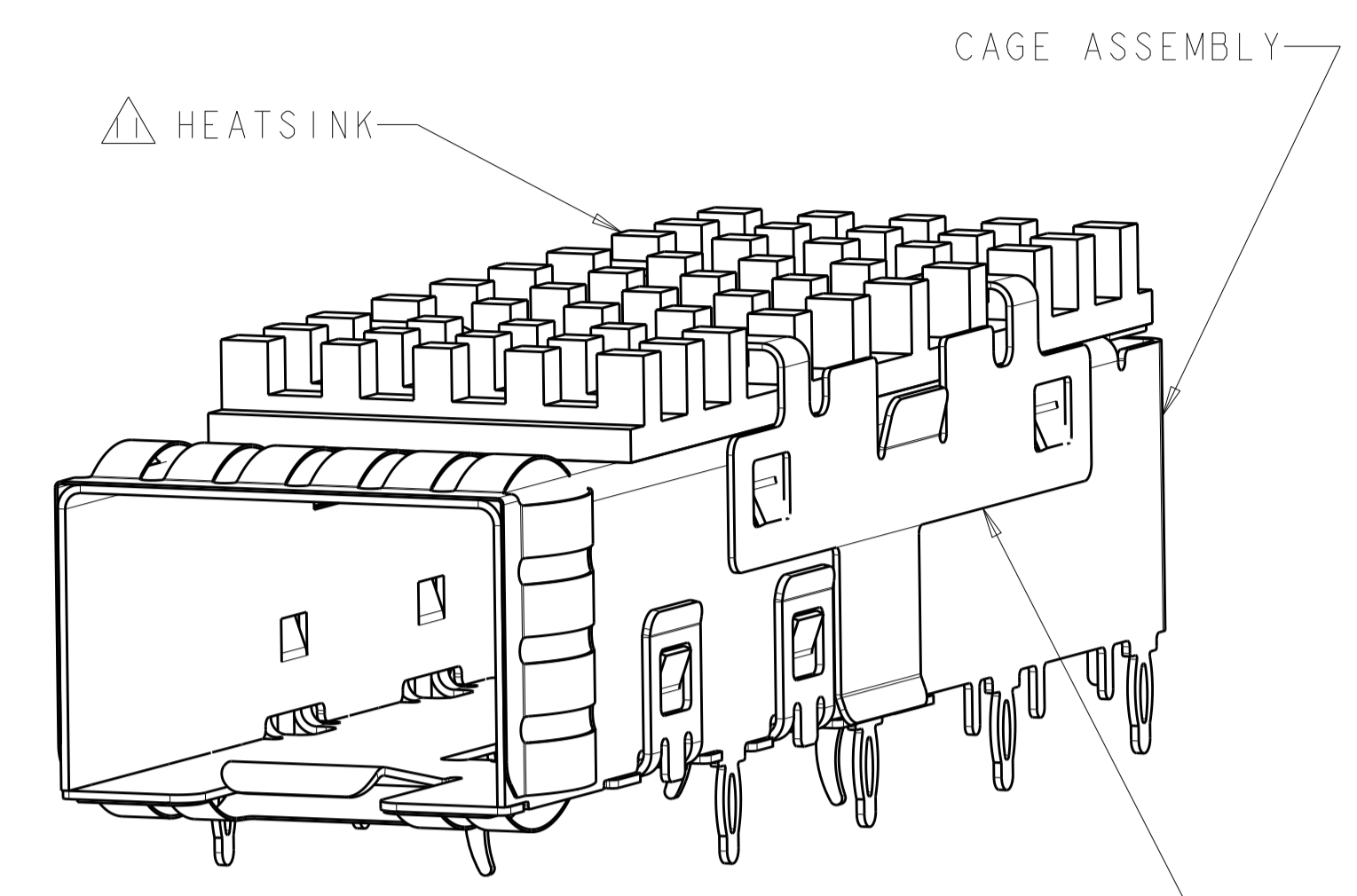
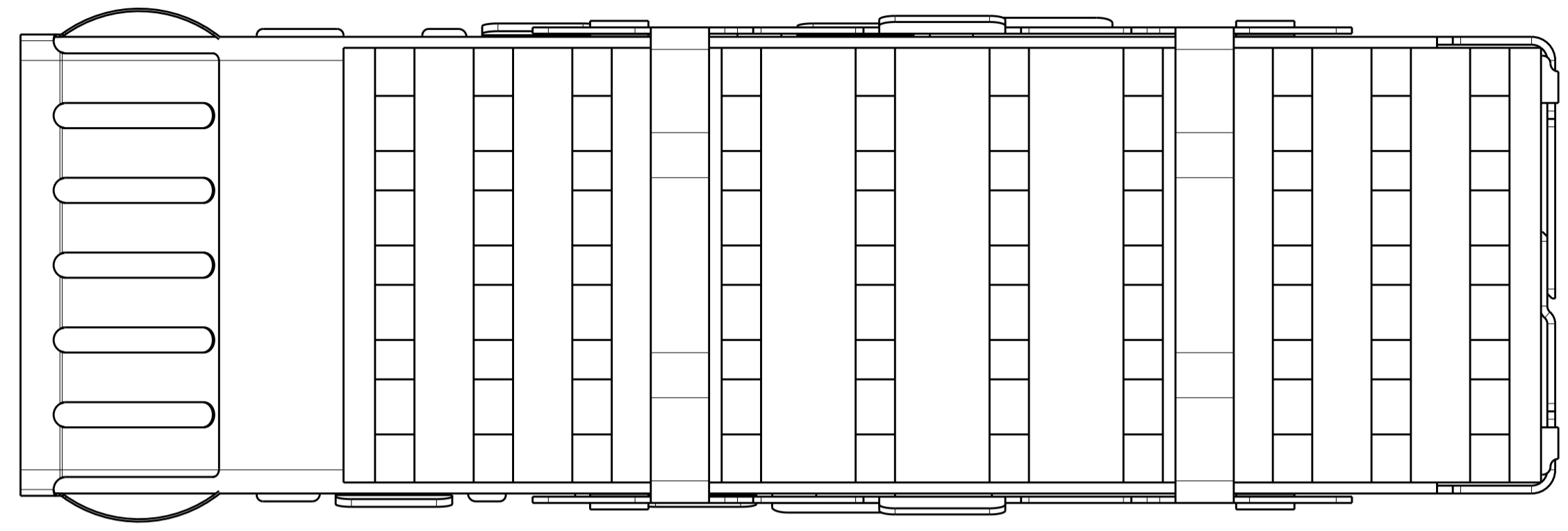
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

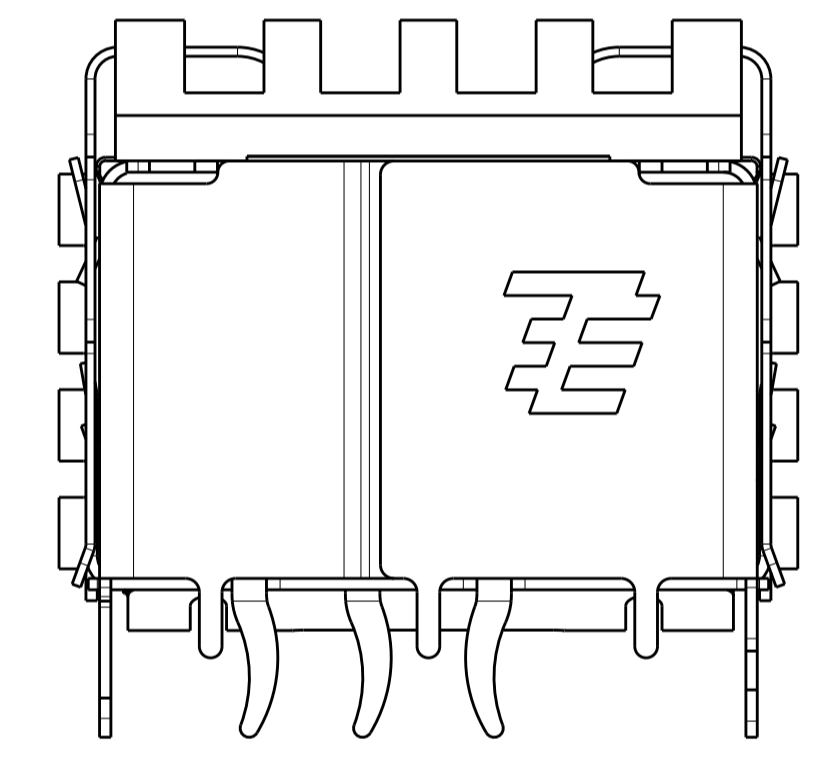
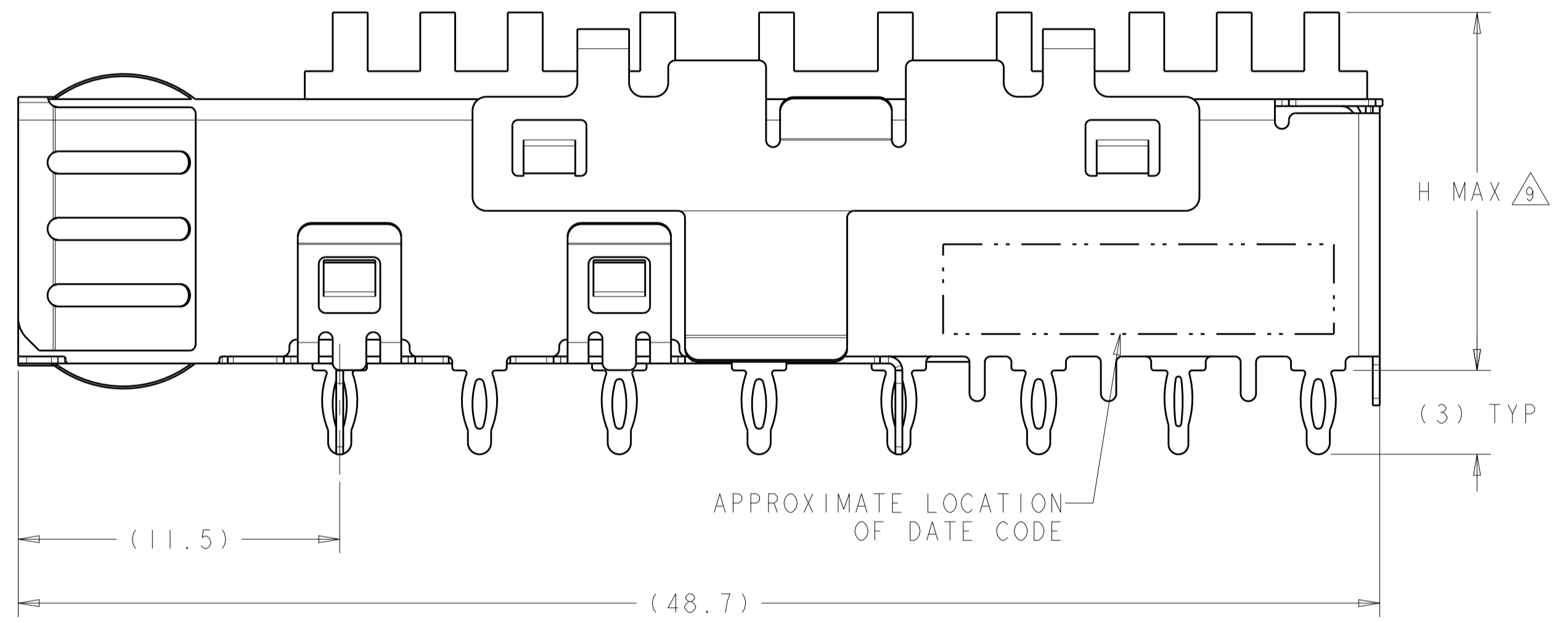
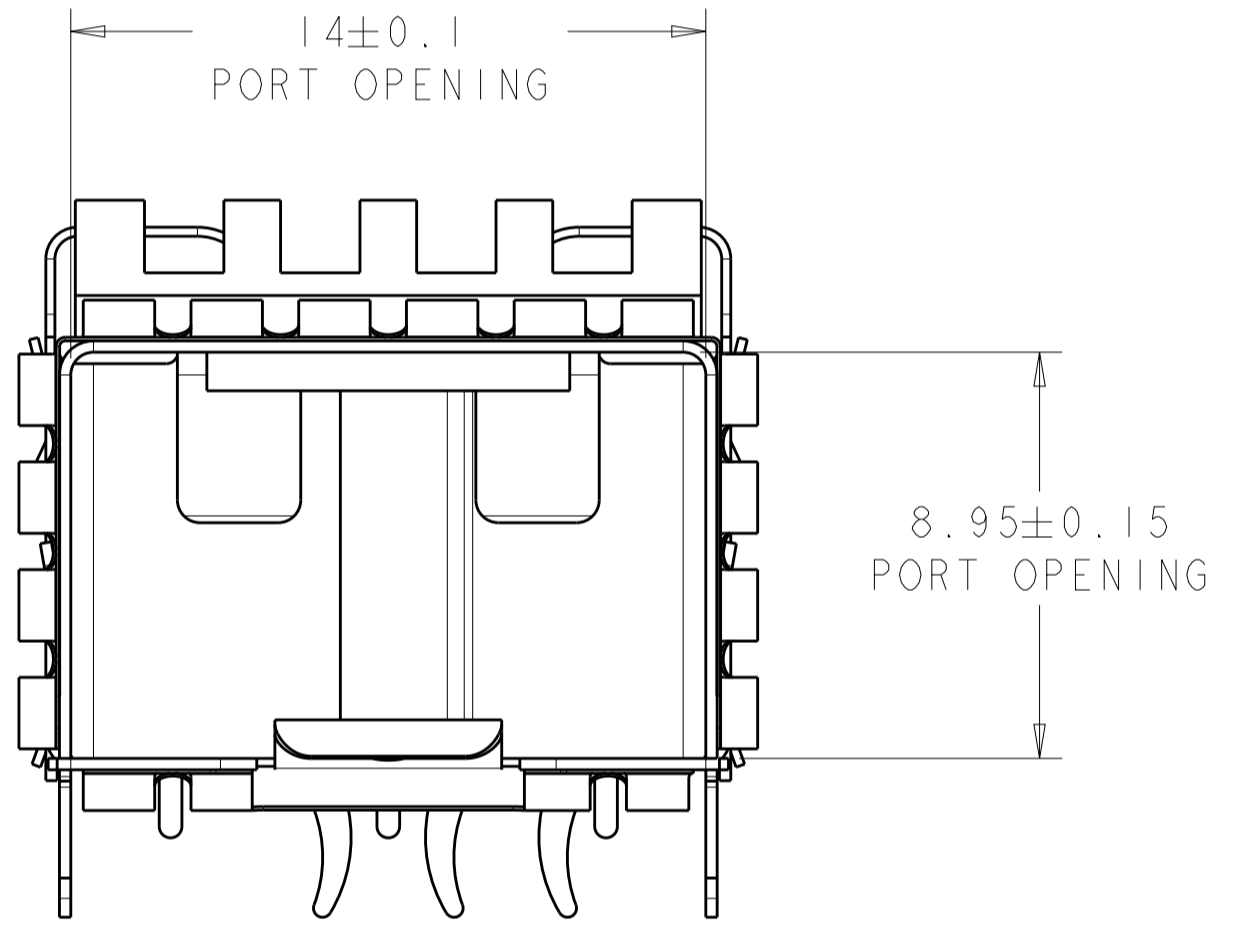


LOC	DIST	REVISIONS					
GP	00	P	LTN	DESCRIPTION	DATE	DMN	APVD
		D1		REVISED PER ECO-11-004835	11MAR2011	RK	HMR
		E		REVISED PER ECO-11-019224	16JAN2012	TX	AC
		E1		ADD PART NUMBER WITH TAPE	27JUL2012	TX	AC
		F		REVISED PER ECO-12-021462	10DEC2012	TX	AC

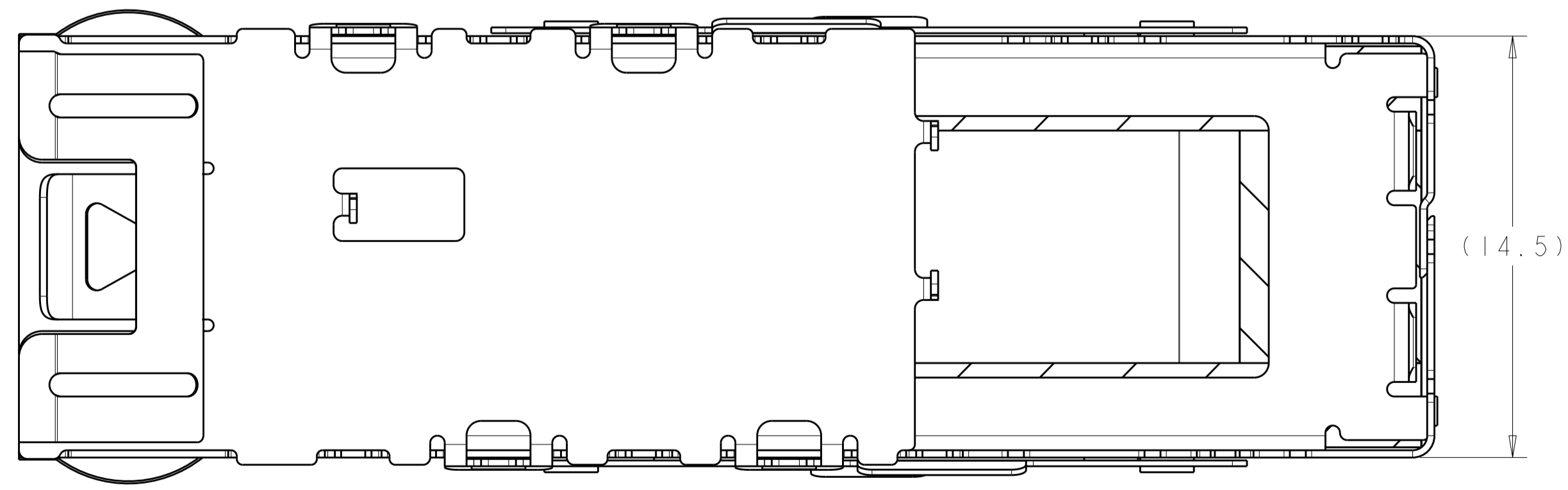
- 1. MATERIAL:  
 CAGE - 0.25mm THICK NICKEL SILVER ALLOY  
 HEATSINK - ALUMINUM  
 HEATSINK CLIP - STAINLESS STEEL  
 EMI SPRING(S) - COPPER ALLOY
- 2. FINISH:  
 HEATSINK - ELECTROLESS NICKEL  
 HEATSINK CLIP - PASSIVATE  
 EMI SPRING(S) - 0.8um MIN MATTE TIN OVER 0.8um MIN NICKEL,  
 NON-PLATED EDGES PERMISSIBLE.
- 3. MATES WITH SFP MSA COMPLIANT TRANSCEIVERS.
- 4. PADS AND VIAS CHASSIS GROUND.
- 5. DATUM AND BASIC DIMENSION ESTABLISHED BY CUSTOMER.
- 6. MINIMUM PC BOARD THICKNESS:  
 SINGLE SIDED = 1.50mm  
 DOUBLE SIDED = 3.00mm
- 7. REFERENCE APPLICATION SPEC. 114-13120, HOLE A, FOR  
 RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.



2007464-1  
 SCALE 5:1



- 8. REFERENCE APPLICATION SPEC. 114-13120, HOLE C, FOR  
 RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.
- 9. DIMENSION APPLIES PRIOR TO INSERTION OF SFP MODULE.
- 10. CAGE ASSEMBLY, HEATSINK CLIP AND HEATSINK SHIPPED  
 ASSEMBLED.
- 11. HEAT SINK REFERENCE PART NUMBERS:  
 1829903-2 = 4.2 HIGH - PCI  
 1829904-2 = 6.5 HIGH - SAN  
 1829905-2 = 13.5 HIGH - NETWORKING
- 12. REMOVED



DESCRIPTION	H MAX	APPLICATION	PART NUMBER
W/ INSULATING TAPE	22.8	NETWORKING	2007464-4
W/O INSULATING TAPE	22.8	NETWORKING	2007464-3
W/O INSULATING TAPE	15.8	SAN	2007464-2
W/O INSULATING TAPE	13.5	PCI	2007464-1

THIS DRAWING IS A CONTROLLED DOCUMENT. DMN Z.M.REAM 20NOV2007  
 CHK M.R.SCHMITZ 20NOV2007  
 APVD R.H.WERTZ 20NOV2007

**STE** TE Connectivity

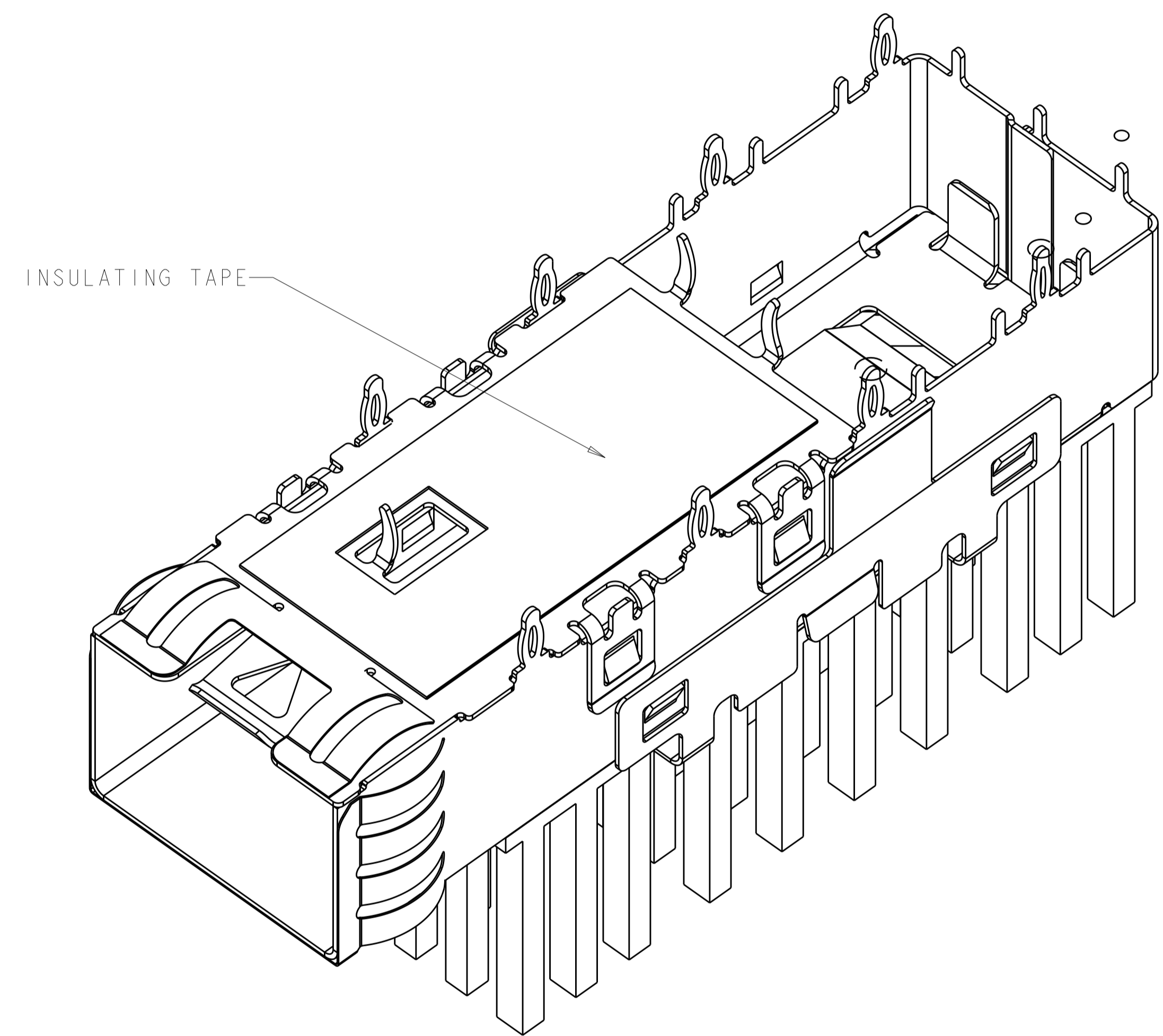
NAME SFP+ 1X1 CAGE ASSEMBLY, PRESS-FIT PRESS-FIT, EMI SPRINGS WITH HEATSINK

PRODUCT SPEC 108-2364  
 APPLICATION SPEC 114-13120

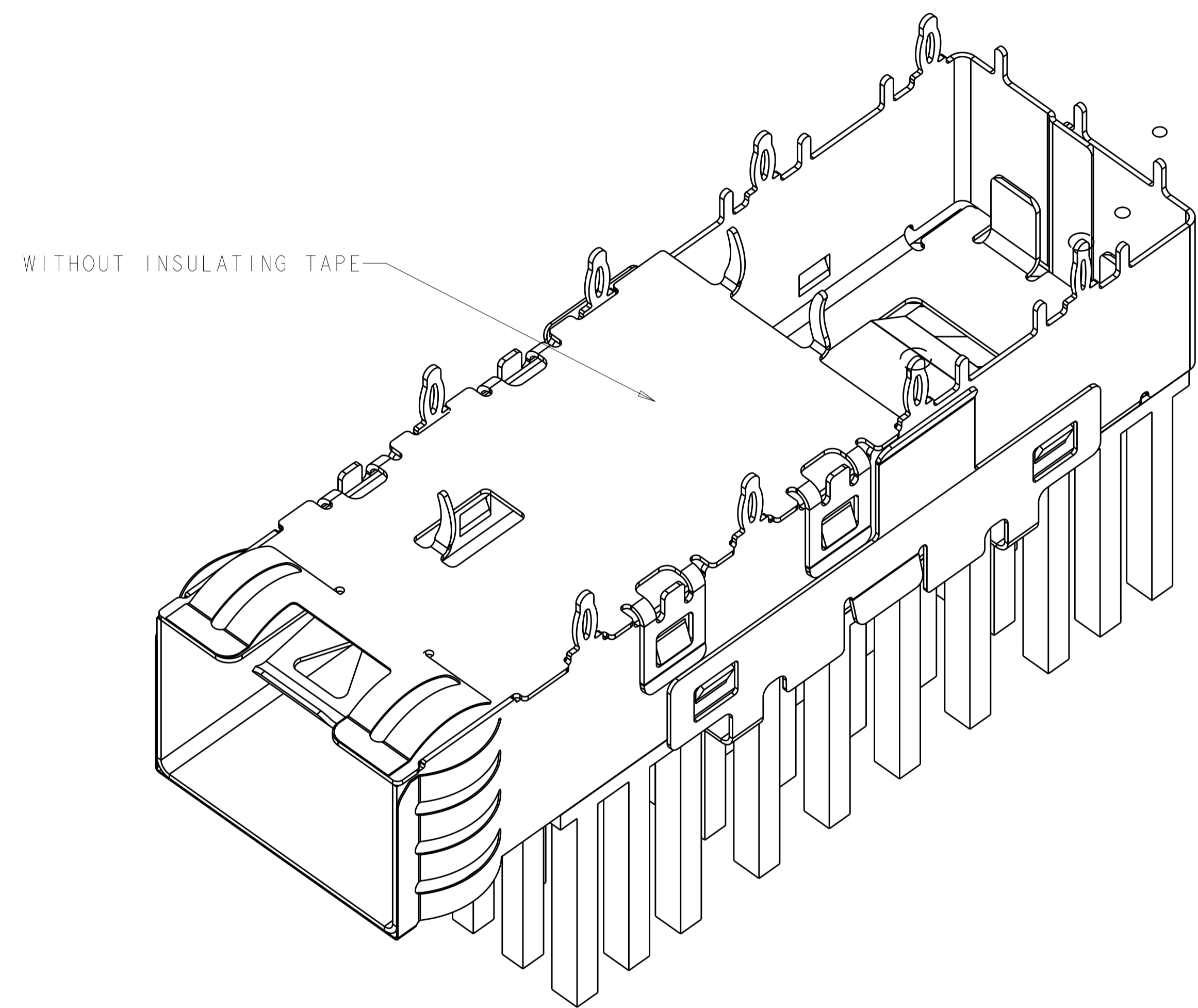
SIZE CAGE CODE DRAWING NO RESTRICTED TO  
 A100779C=2007464

MATERIAL FINISH  
 Customer Drawing SCALE 2 SHEET 1 OF 4 REV F

LOC		DIST		REVISIONS			
GP	00	P	LYN	DESCRIPTION	DATE	DMN	APVD
		-		SEE SHEET 1			



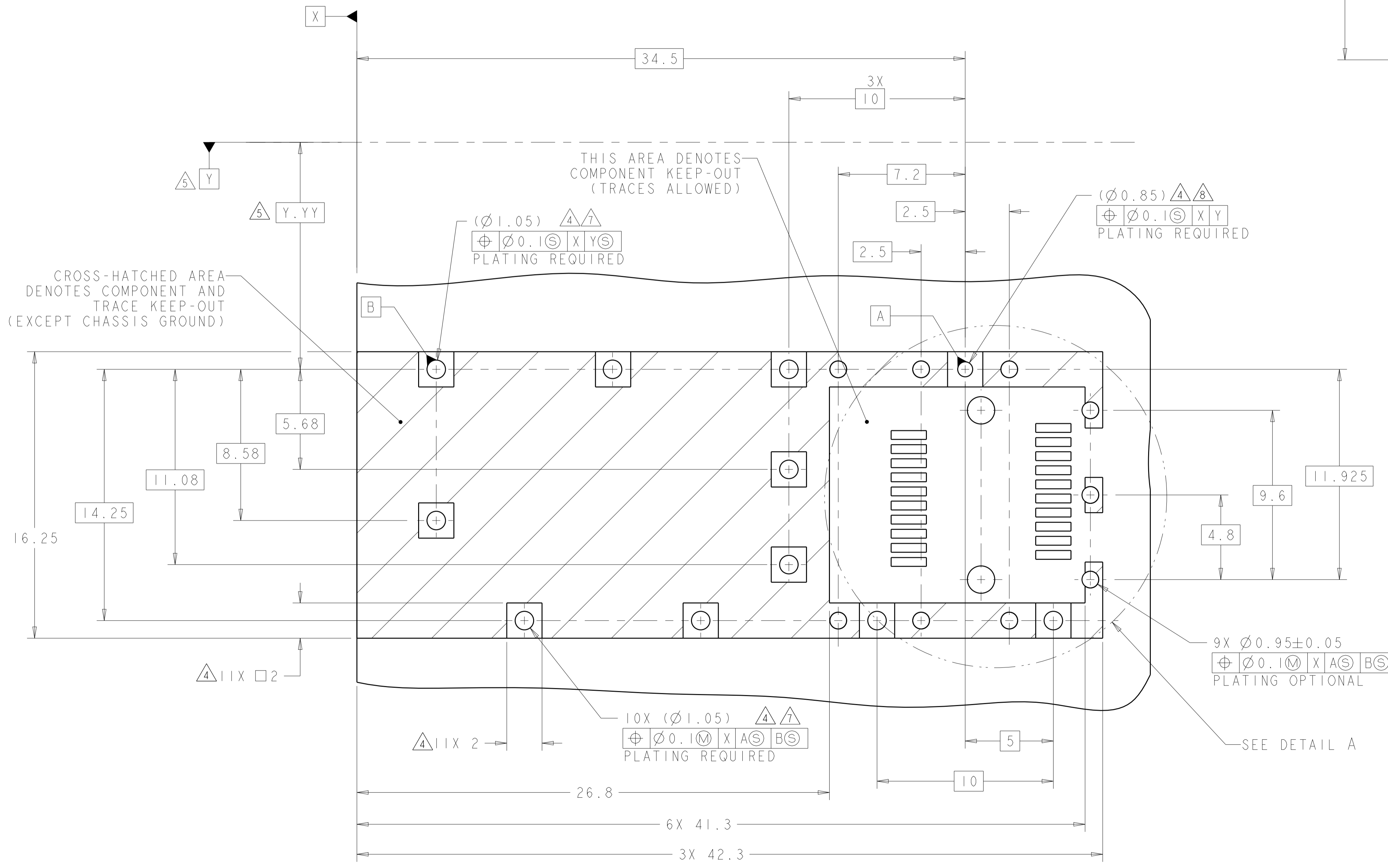
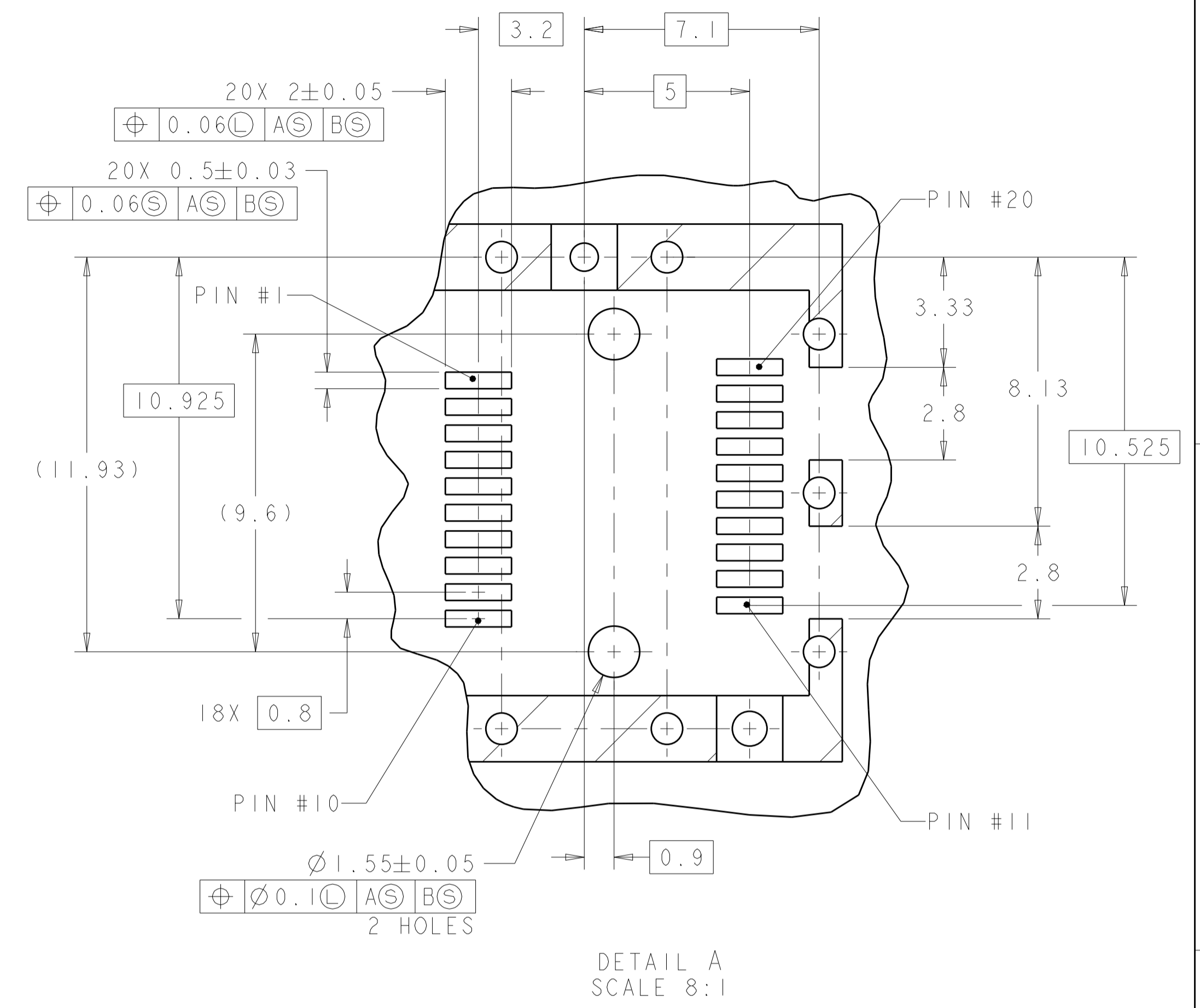
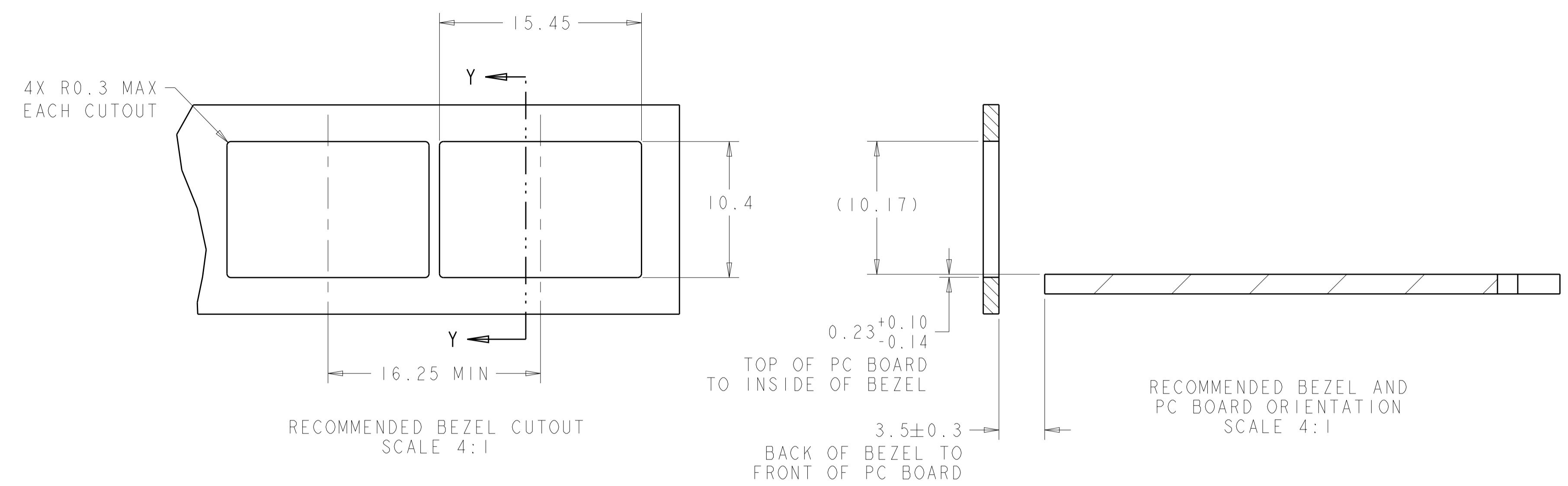
2007464-4 AS SHOWN WITH INSULATING TAPE



2007464-3 AS SHOWN WITHOUT INSULATING TAPE  
 2007464-1,2 ALSO WITHOUT INSULATING TAPE

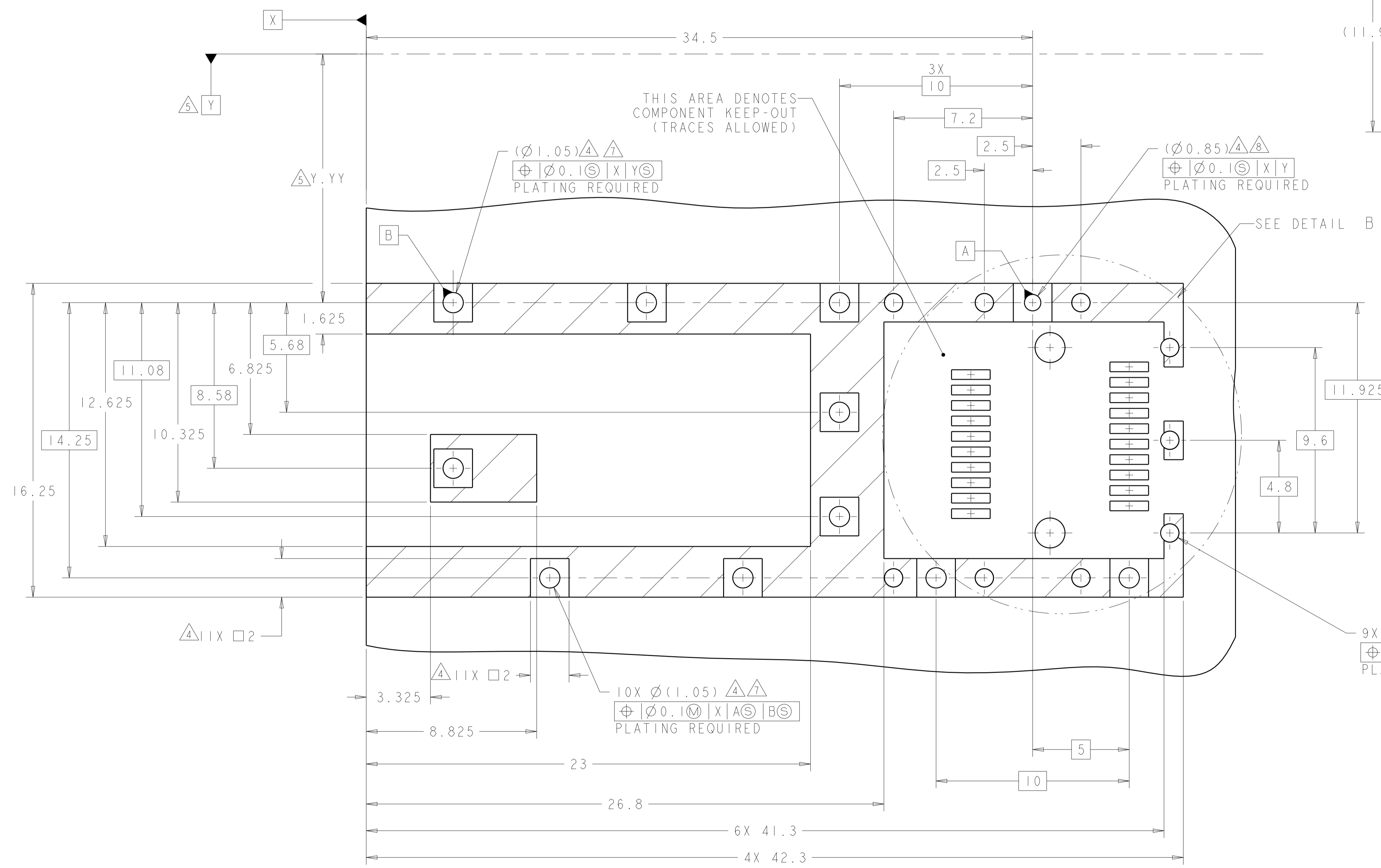
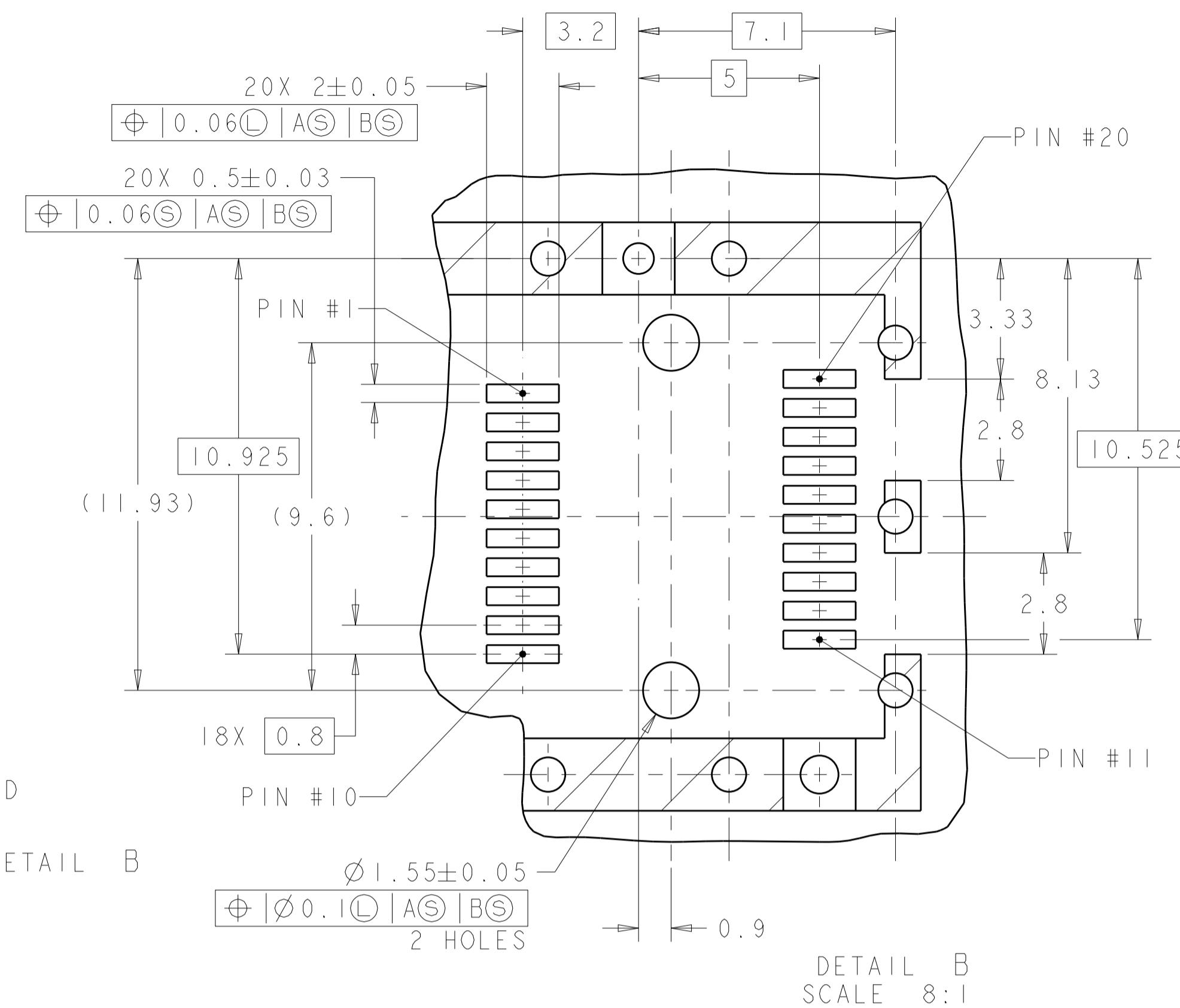
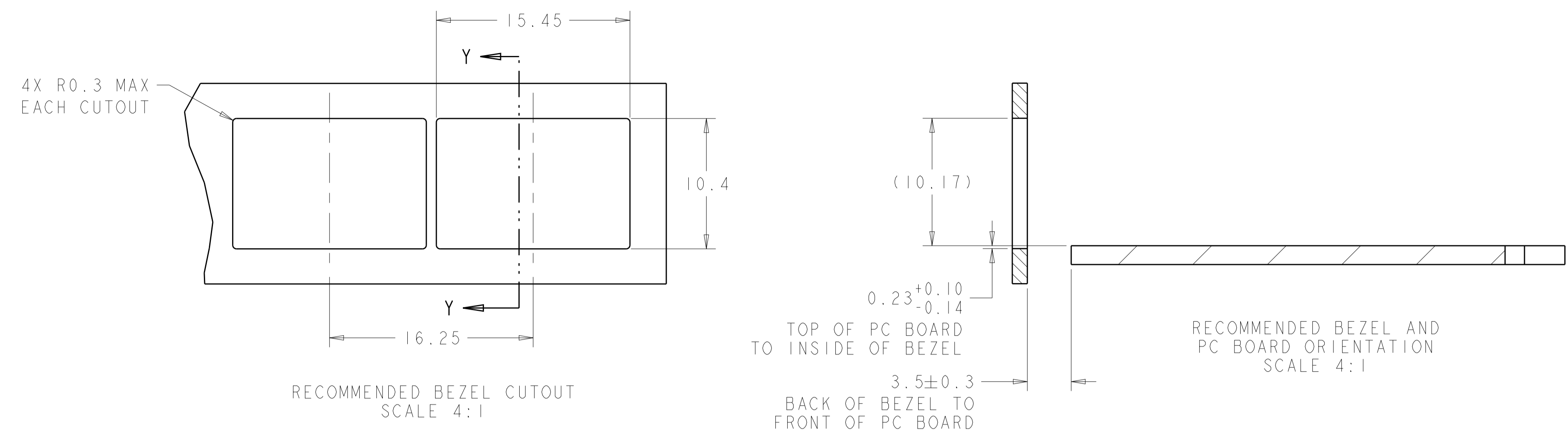
THIS DRAWING IS A CONTROLLED DOCUMENT.		DMN	Z.M.BEAM	20NOV2007	<b>STE</b> TE Connectivity
DIMENSIONS:		CHK	M.R.SCHMITZ	20NOV2007	
mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	APVD	R.H.WERTZ	20NOV2007	NAME SFP+ 1X1 CAGE ASSEMBLY, PRESS-FIT PRESS-FIT, EMI SPRINGS WITH HEATSINK
	0 PLC ±0.1	PRODUCT SPEC			
	1 PLC ±0.1	108-2364			SIZE CAGE CODE DRAWING NO A100779C=2007464
	2 PLC ±0.1	APPLICATION SPEC			
	3 PLC ±0.05	114-13120			RESTRICTED TO Customer Drawing
	4 PLC ±0.05	WEIGHT			
	ANGLES ±0.05				SCALE 2 SHEET 2 OF 4 REV F
MATERIAL	FINISH				

LOC	DIST	REV	DESCRIPTION	DATE	OWN	APVD
GP	00		SEE SHEET 1			



THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN: Z.M. REAM 20NOV2007	TE Connectivity
DIMENSIONS: mm		CHK: M.B. SCHMITZ 20NOV2007	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: R.H. WERTZ 20NOV2007	NAME: SFP+ IXI CAGE ASSEMBLY, PRESS-FIT PRESS-FIT, EMI SPRINGS WITH HEATSINK
0 PLC	±0.1	PRODUCT SPEC	SIZE: CAGE CODE DRAWING NO
1 PLC	±0.1	108-2364	RESTRICTED TO
2 PLC	±0.1	APPLICATION SPEC	A100779C=2007464
3 PLC	±0.05	114-13120	SCALE 2 SHEET 3 OF 4 REV F
4 PLC	±0.05	WEIGHT	
ANGLES	±0.05	Customer Drawing	
MATERIAL	FINISH		

LOC	DIST	REV	DATE	APPD	REVISED
GP	00				
					SEE SHEET 1



RECOMMENDED PCB LAYOUT FOR WITH INSULATING TAPE PART SCALE 8:1

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DIMENSIONS: mm		CHK M.R.SCHMITZ 20NOV2007	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APPD B.H.WERTZ 20NOV2007	NAME SFP+ IXI CAGE ASSEMBLY, PRESS-FIT PRESS-FIT, EMI SPRINGS WITH HEATSINK
0 PLC ±0.1		PRODUCT SPEC 108-2364	SIZE CAGE CODE DRAWING NO RESTRICTED TO
1 PLC ±0.1		APPLICATION SPEC 114-13120	A100779C=2007464
2 PLC ±0.1		WEIGHT	SCALE 2 SHEET 4 OF 4 REV F
3 PLC ±0.05		Customer Drawing	
4 PLC ±0.05			
ANGLES ±0.05			
FINISH			